Rochester Electronics

Datasheet

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
    - Class Q Military
    - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

    - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

FAIRCHILD SEMICONDUCTOR™

August 1986
Revised March 2000

DM74LS244
Octal 3-STATE Buffer/Line Driver/Line Receiver

General Description

These buffers/line drivers are designed to improve both the performance and PC board density of 3-STATE buffers/drivers employed as memory-address drivers, clock drivers, and bus-oriented transmitters/receivers. Featuring 400 mV of hysteresis at each low current PNP data line input, they provide improved noise rejection and high fanout outputs and can be used to drive terminated lines down to 133Ω.

Features

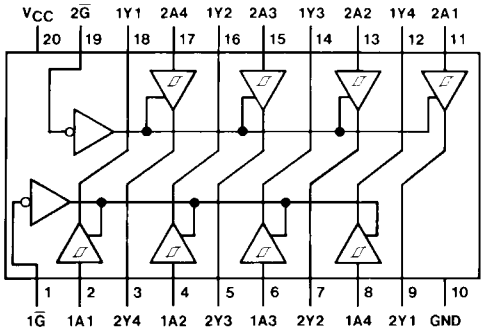
- 3-STATE outputs drive bus lines directly
- PNP inputs reduce DC loading on bus lines
- Hysteresis at data inputs improves noise margins
- Typical I_{OL} (sink current) 24 mA
- Typical I_{OH} (source current) −15 mA
- Typical propagation delay times
  - Inverting 10.5 ns
  - Noninverting 12 ns
- Typical enable/disable time 18 ns
- Typical power dissipation (enabled)
  - Inverting 130 mW
  - Noninverting 135 mW

Ordering Code:

Order Number	Package Number	Package Description
DM74LS244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
DM74LS244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
DM74LS244N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Function Table

Inputs		Output
$\overline{G}$	A	Y
L	L	L
L	H	H
H	X	Z

L = LOW Logic Level
H = HIGH Logic Level
X = Either LOW or HIGH Logic Level
Z = High Impedance

Absolute Maximum Ratings(Note 1)

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	0°C to +70°C
Storage Temperature Range	−65°C to +150°C

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Recommended Operating Conditions

Symbol	Parameter	Min	Nom	Max	Units
V_{CC}	Supply Voltage	4.75	5	5.25	V
V_{IH}	HIGH Level Input Voltage	2			V
V_{IL}	LOW Level Input Voltage			0.8	V
I_{OH}	HIGH Level Output Current			−15	mA
I_{OL}	LOW Level Output Current			24	mA
T_A	Free Air Operating Temperature	0		70	°C

Electrical Characteristics

over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ (Note 2)	Max	Units
V_I	Input Clamp Voltage	V_{CC} = Min, I_I = −18 mA				−1.5	V
HYS	Hysteresis ($V_{T+} - V_{T-}$) Data Inputs Only	V_{CC} = Min		0.2	0.4		V
V_{OH}	HIGH Level Output Voltage	V_{CC} = Min, V_{IH} = Min V_{IL} = Max, I_{OH} = −1 mA		2.7			V
		V_{CC} = Min, V_{IH} = Min V_{IL} = Max, I_{OH} = −3 mA		2.4	3.4		
		V_{CC} = Min, V_{IH} = Min V_{IL} = 0.5V, I_{OH} = Max		2			
V_{OL}	LOW Level Output Voltage	V_{CC} = Min V_{IL} = Max V_{IH} = Min	I_{OL} = 12 mA			0.4	V
			I_{OL} = Max			0.5	
I_{OZH}	Off-State Output Current, HIGH Level Voltage Applied	V_{CC} = Max V_{IL} = Max V_{IH} = Min	V_O = 2.7V			20	µA
I_{OZL}	Off-State Output Current, LOW Level Voltage Applied		V_O = 0.4V			−20	µA
I_I	Input Current at Maximum Input Voltage	V_{CC} = Max	V_I = 7V			0.1	mA
I_{IH}	HIGH Level Input Current	V_{CC} = Max	V_I = 2.7V			20	µA
I_{IL}	LOW Level Input Current	V_{CC} = Max	V_I = 0.4V	−0.5		−200	µA
I_{OS}	Short Circuit Output Current	V_{CC} = Max (Note 3)		−40		−225	mA
I_{CC}	Supply Current	V_{CC} = Max, Outputs Open	Outputs HIGH		13	23	mA
			Outputs LOW		27	46	
			Outputs Disabled		32	54	

Note 2: All typicals are at V_{CC} = 5V, T_A = 25°C.

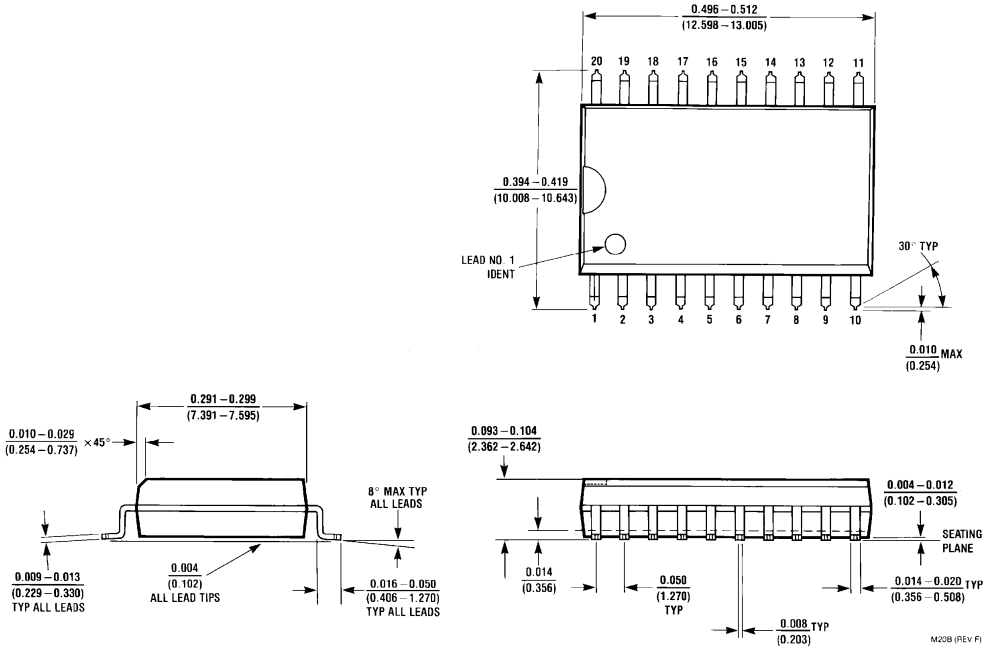
Note 3: Not more than one output should be shorted at a time, and the duration should not exceed one second.

Switching Characteristics

at V_{CC} = 5V, T_A = 25°C

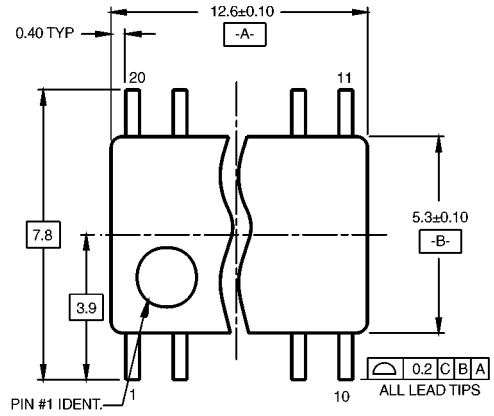
Symbol	Parameter	Conditions	Max	Units
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	C_L = 45 pF R_L = 667Ω	18	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	C_L = 45 pF R_L = 667Ω	18	ns
t_{PZL}	Output Enable Time to LOW Level	C_L = 45 pF R_L = 667Ω	30	ns
t_{PZH}	Output Enable Time to HIGH Level	C_L = 45 pF R_L = 667Ω	23	ns
t_{PLZ}	Output Disable Time from LOW Level	C_L = 5 pF R_L = 667Ω	25	ns
t_{PHZ}	Output Disable Time from HIGH Level	C_L = 5 pF R_L = 667Ω	18	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	C_L = 150 pF R_L = 667Ω	21	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	C_L = 150 pF R_L = 667Ω	22	ns
t_{PZL}	Output Enable Time to LOW Level	C_L = 150 pF R_L = 667Ω	33	ns
t_{PZH}	Output Enable Time to HIGH Level	C_L = 150 pF R_L = 667Ω	26	ns

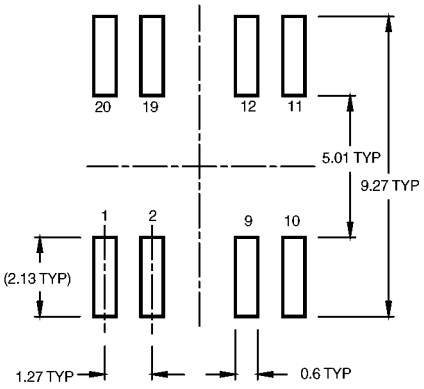
Physical Dimensions inches (millimeters) unless otherwise noted



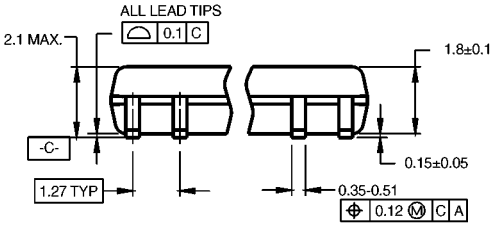
20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

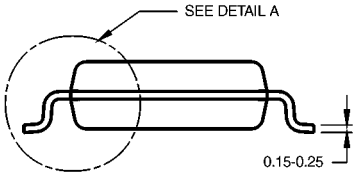




LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



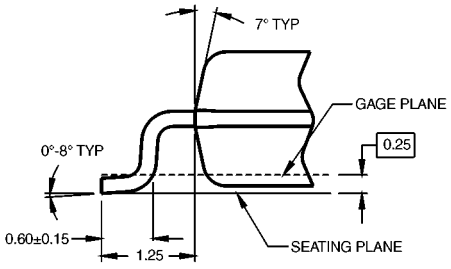
NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

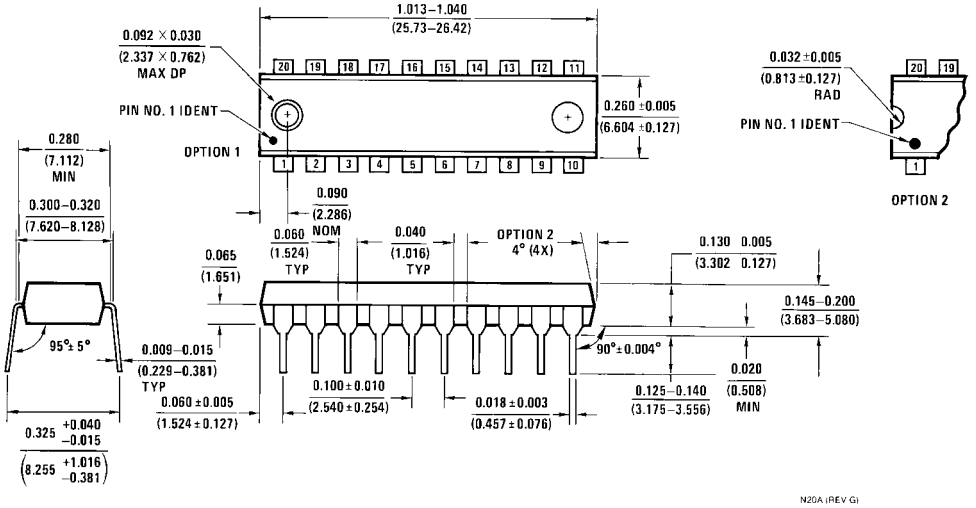
M20DRevB1



DETAIL A

20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N20A